

Military-Grade High-Density Memory

Compact and rugged DDR memory components for SWaP-constrained applications

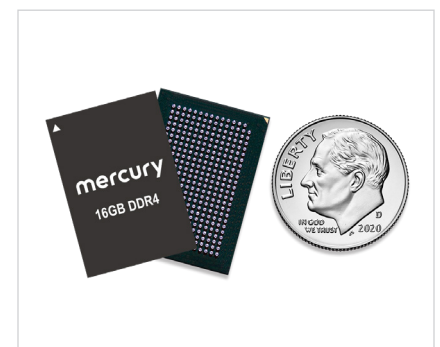
Rugged, high-density memory is a critical element in advanced edge processing. As these systems get smaller and their processing needs increase, memory modules must deliver high-performance in a small form factor. SWaP-optimized, compact BGA packages consisting of multiple stacked die save board space and improve reliability.

Our environmentally tested BGA packaged solutions are manufactured through a trusted supply chain in a DMEA- and AS9100-certified facility. Our relationships with semiconductor suppliers and the ability to redesign and provide form-fit-function (FFF) replacement help mitigate obsolescence risks.

Highlights

- Advanced miniaturization technology resulting in up to 87% space savings
- Compact plastic BGA package consisting of multiple stacked die
- Military-grade performance with DMEA-trusted manufacturing and supply chain
- Military, industrial and commercial temperature ranges

Featured Product DDR4



DDR SDRAM delivers trusted, reliable performance in a compact, ruggedized package

Benefits

- Limit supply chain complexity and simplify board design with up to 93% component reduction
- Recognize full program life through supplier managed DMS strategy
- Operate with confidence in the harshest environments with 100% burn-in and electrical testing

Features

- 128 MB to 16 GB capacity
- Transfer speeds up to 2400 Mb/s
- Eutectic solder balls for superior board-level reliability
- 72-bit-wide data bus to support error detection and correction (EDAC)
- Moisture-sensitivity level (MSL) 3

Applications

- Aircraft flight decks
- Unmanned aerial vehicles
- Defense weapons
- Vibration-intensive environments
- Mission-critical applications
- Medical imaging
- Downhole drilling

DELIVERING TRUSTED MEMORY SOLUTIONS

Mercury Systems is the leader in making trusted, secure mission-critical technologies profoundly more accessible to aerospace and defense. We have successfully commercialized our miniaturization technology for decades, enabling more sensor functionality in smaller and more lightweight mission computing subsystems. Our memory solutions are manufactured in a Defense Microelectronics Activity (DMEA)-accredited facility and are assured for trusted supply chain.

To learn more about our DDR products, visit: mrcy.com/ddr.



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Learn more

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